GROUNDING AN	D BONDING CON For use of this form, so			TING FACILITIES	
1. FACILITY			2. DATE (YYYYMMDD)		
3. LOCATION			4. INSPECTOR		
5. GENERAL CONDITION					
EXCELLENT (GOOD	POOR	UNACCEPTABLE		
6. SPECIFIC DEFICIENCIES					
LOCATION	DEFICIENCIES				
7. RESISTANCE (Use double balanced 1.0 milli-ohm)	dc bridge or approved	bond resistance mete	er and identify those bo	nds whose resistance is greater than	
LOCATION	DEFICIENCIES				
8. INEFFECTIVE BONDING JUMPERS					
LOCATION	MATERIAL	LENGTH	SIZE	DEFICIENCIES	